

## ABSTRACT

The present invention aims to improve the polishing rate during the polishing process of semiconductor substrates, hard disk substrates or the like by using a polishing composition containing silica particles, water, a basic substance and an inorganic salt, and by a polishing method using such a polishing composition.

This polishing composition can be produced by mixing silica particles, water, a basic substance and an inorganic salt, and it is also obtained by adding an inorganic salt into a conventionally known alkaline polishing composition containing silica particles.

As the inorganic salt, there is used an alkali metal salt or an ammonium salt such as KCl, K<sub>2</sub>SO<sub>4</sub>, KNO<sub>3</sub>, NaCl, Na<sub>2</sub>SO<sub>4</sub>, NaNO<sub>3</sub>, NH<sub>4</sub>Cl, NH<sub>4</sub>NO<sub>3</sub>, and (NH<sub>4</sub>)<sub>2</sub>SO<sub>4</sub>.

A polishing composition, wherein silica particles do not agglomerate when an inorganic salt is added, can improve the polishing rate significantly.